



CBR-SMD RF C0G, Ceramic, 8.5 pF, +/-0.25 pF, 100 VDC, C0G, SMD, Fixed, RF, Ultra High Q, Low ESR, Class I, 0603



General Information	
Series	CBR-SMD RF COG
Style	SMD Chip
Description	SMD, Fixed, RF, Ultra High Q, Low ESR, Class I
Features	Ultra High Q, Low ESR, Class I
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Typical Component Weight	5.29 mg
Notes	Solder Wave or Solder Reflow.
Shelf Life	78 Weeks
MSL	1

Dimensions	
Chip Size	0603
L	1.6mm +/-0.1mm
W	0.8mm +/-0.1mm
Т	0.8mm +/-0.07mm
В	0.4mm +/-0.15mm

W	0.8mm +/-0.1mm	Voltage DC	100 VDC
Т	0.8mm +/-0.07mm	Dielectric Withstanding Voltage	250 VDC
В	0.4mm +/-0.15mm	Temperature Range	-55/+125°C
		Temp. Coefficient	COG
Packaging Specifications		Dissipation Factor	0.175%
Packaging	T&R, 180mm, Plastic Tape	Aging Rate	0% Loss/Decade Hour
Packaging Quantity	4000	Insulation Resistance	10 GOhms
		a	

Specifications	
Capacitance	8.5 pF
Tolerance	+/-0.25 pF
Voltage DC	100 VDC
Dielectric Withstanding Voltage	250 VDC
Temperature Range	-55/+125°C
Temp. Coefficient	COG
Dissipation Factor	0.175%
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	10 GOhms
Quality Factor	570

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